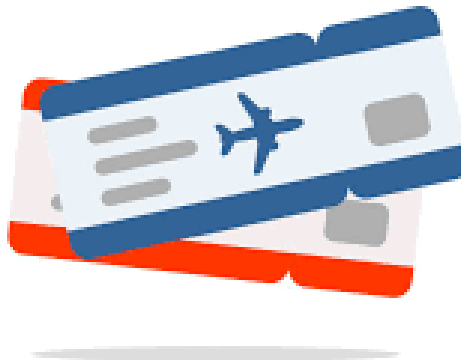




Co-funded by  
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## SILEO Hack Days & Travel Vouchers scheme Report



## D3.2 - SILEO Hack Days & Travel Vouchers scheme

Deliverable Control Page			
<b>Deliverable Title</b>	SILEO Hack Days & Travel Vouchers scheme		
<b>Deliverable Number</b>	3.2		
<b>WP number</b>	3		
<b>Author(s)</b>	Rete di Imprese Luce in Veneto		
<b>Short Description</b>	Report on the execution of n° 2 SILEO international Hack days (in EN) and the related Travel-voucher scheme procedures (open call, selection, execution) and impact.		
<b>Contributors</b>	All PPs		
<b>Type</b> R = Report, DEC=Websites, videos etc. O = Other,	R		
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## D3.2 - SILEO Hack Days & Travel Vouchers scheme

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## D3.2 - SILEO Hack Days & Travel Vouchers scheme

### Premises

Small and medium-sized enterprises are less resilient to crises because they often lack the necessary resources and are thus more affected by supply chain disruptions. The three-year SILEO project aims to help SMEs from the lighting and furniture industry become resilient to crises and better manage market changes with a range of financial and non-financial measures.

Since September 2022, seven European clusters, coordinated by the European Lighting Cluster Alliance – ELCA work together to supporting SMEs around Europe. The SILEO project is co-funded by the SMP program under the SMP-COSME-2021-CLUSTER call. More information about the project are available on its [webpage](#) hosted by ELCA.

The project aims to create an open, innovation-friendly environment for business modernization. To reduce the risk of introducing new technologies, SMEs are accompanied by experts and supported with sector-specific cost-benefit analyses. SILEO Consortium aspires to capture all the digitalisation potential for the furniture and lighting SMEs with a concerted effort channelled through an open and inclusive ecosystem for innovation and technology business upgrading with accompanying business support measures including expert consultancy, business resilience building guidance, reinforced by direct financial support schemes and talent placement services to help companies attract talent.

The project proposes a direct financial funding scheme through financial support to third parties (cascade funding), joint talent placement services and internationalization actions to accelerate the recovery of lighting and furniture SMEs, support them in becoming more resilient to future shocks, better prepared for disruptions in supply and value chains, greener in business operations and stronger connected to technology ecosystems through strategic partnering.

The SILEO Consortium envisaged 5 typologies of Financial Support to Third Parties - FSTP activated through open calls for cascade funding, during the project course. Among them, specific calls offering SILEO Hack Day Travel Vouchers, were put in place, to support lighting and furniture SMEs' participation in the project hackathon events in Romania and Italy and help them take an active part in the match-making with technology providers.

Two 1-day international hackathons "SILEO Tech Challenge - Hack Days to Drive Innovation in Lighting & Furniture" were organized within the SILEO Eurocluster project:

- **SILEO Hack Day "Navigating Challenges and Tech Solutions for SMEs in the furniture & lighting Industry" organized by Transylvanian Furniture Cluster in Cluj-Napoca, Romania on 13-14.06.2024.**
- **SILEO Hack Day "IMPACT - Development of innovative business ideas for SMEs in the Furniture & Lighting industry" organized by Rete di Imprese Luce in Veneto in Padua, Italy on 16.10.2024.**

Each SILEO hackathon served as a collaborative platform connecting SMEs in the lighting and furniture sectors with technology providers such as Digital Innovation Hubs, Competence Centers, incubators, and tech-savvy companies. These providers showcased their solutions to tackle the pre-identified "SILEO SME Challenges", which focus on digital and circular transitions. The hackathons aimed to promote lasting innovation by presenting advanced technologies and disruptive solutions to address real-world business challenges within the lighting and furniture industries, supporting post-pandemic recovery and resilience.

Participating SMEs gained a valuable opportunity to explore new technologies, gain insights, and engage directly with solution providers offering tailored innovations for the manufacturing, logistics, and trade processes specific to their sectors.

## D3.2 - SILEO Hack Days & Travel Vouchers scheme

The two SILEO Hackathons were organized in the following phases:

- Phase 1: Selection of the venue and timing by the organizing partner.
- Phase 2: Organization and launch of the Travel Voucher Open Call for SILEO SMEs and tech-savvy companies, managed by the SILEO Consortium in alignment with FSTP guidelines.
- Phase 3: Selection of SMEs awarded Travel Vouchers and tech-savvy companies to participate in hackathons.
- Phase 4: Finalization of logistics and signature of SILEO Sub-Grant Agreements with the awarded SMEs
- Phase 5: Event day organization.
- Phase 6: Follow-up and matchmaking

To foster the growth of innovative ideas and investment projects, the SILEO Consortium facilitated the participation of SMEs in two impactful hackathon events, helping them actively engage in matchmaking with technology providers through the SILEO Hack Day Travel Vouchers.

The travel vouchers were available for two distinct categories of SMEs:

- ✓ SMEs operating within the lighting or furniture industries.
- ✓ Tech-savvy SMEs with a focus on advanced technologies and green solutions.

The travel vouchers were allocated through two separate Open Calls, each aligned with EU regulations (specifically FSTP) and the terms outlined in the Grant Agreement. These calls were carefully structured and launched three months before each respective hackathon event, remaining open for a minimum of 60 days. These calls were hosted on the Cluster Submission Platform (<https://clustersubmissionplatform.eu/>).

The calls were widely promoted across multiple platforms, including the ECCP Platform, EEN websites, the Funding & Tenders Portal, and the websites of SILEO project partners. In addition, promotional efforts spanned project communication channels, institutional networks of the project partners, regional authorities, local EEN nodes, and various social media channels.

Importantly, the travel vouchers were awarded to SMEs as organizations rather than to individuals, allowing the funds to cover the travel expenses for multiple participants from the selected SMEs, thus encouraging broader involvement in the hackathon events.

### 1. Hack Day in Cluj-Napoca (Romania) on 13-14.06.2024



SILEO Consortium launched a specific open call “**SILEO Open Call for Hack Day Travel Vouchers – Romania**”, designed to support SMEs in participating in the Hack Day event “Navigating Challenges and Tech Solutions for SMEs in the furniture & lighting Industry” organized by Transylvanian Furniture Cluster in Cluj-Napoca, Romania on 13-14.06.2024.

The Open Call ran from 20.02.2024 (10:00 AM) to 26.04.2024 (17:00 PM) via the SILEO Clusters submission portal at [https://clustersubmissionplatform.eu/eurocluster\\_post/sileo-open-call-travel-vouchers-romania/](https://clustersubmissionplatform.eu/eurocluster_post/sileo-open-call-travel-vouchers-romania/).

The Hack Day in Romania was designed to bring together SMEs operating in the furniture and lighting sectors and tech-savvy SMEs, providing a collaborative environment to address critical

industry challenges and co-develop innovative solutions.

## D3.2 - SILEO Hack Days & Travel Vouchers scheme

In particular, the event focused on tackling key issues faced by the lighting and furniture industries, structured around five main topics:

1. **DIGITAL OPTIMIZATION IN PRODUCTION** - How can companies optimize digital processes throughout the production chain, from design to delivery?
2. **SUSTAINABILITY IN PRODUCTION** - How can companies integrate sustainable practices into the manufacturing process of furniture and lighting?
3. **DIGITAL CUSTOMER EXPERIENCE** - How can companies innovate in terms of digital customer experience, from purchase to customization?
4. **ENERGY EFFICIENCY IN LIGHTING** - How can technological solutions improve the energy efficiency of lighting systems?
5. **CIRCULAR ECONOMY IN FURNITURE & LIGHTING** - How can companies implement circular economy models for their products?

This initiative provided SMEs with an opportunity to address real challenges, exchange ideas, and collaborate on innovative solutions to advance the furniture and lighting industries.

### 1.1 Travel voucher categories and funding

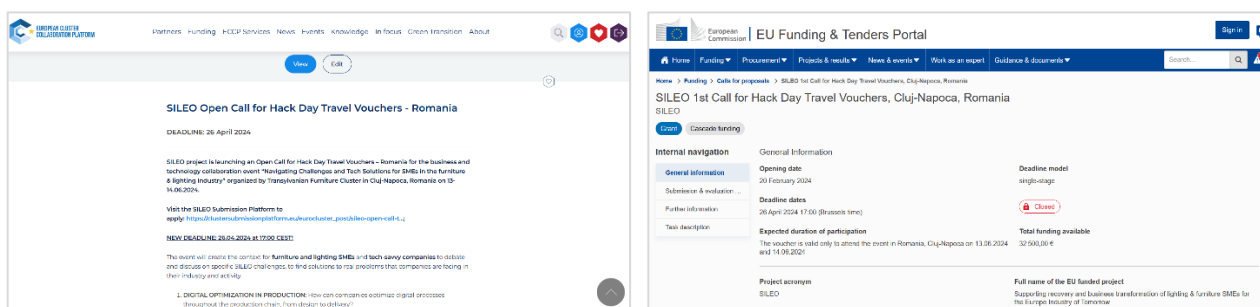
To encourage participation, **65 travel vouchers** were made available and divided into two categories:

- **50 travel vouchers** for SMEs in the lighting or furniture sectors.
- **15 travel vouchers** for tech-savvy SMEs, specializing in innovative and green solutions.

Fundings were allocated based on the distance between the SME's location (legal address) and the Hack Day event venue:

- ❖ € 250 for companies located between 25-250km from Cluj-Napoca.
- ❖ € 500 for companies located 251-500 or more away.

The Open Call was extensively promoted through SILEO's social media channels, particularly on its LinkedIn page, as well as on the websites and social media channels of its partners. Additionally, it was advertised on key platforms such as the European Cluster Collaboration Platform, the Funding & Tenders portal, and various relevant industry and magazine websites.



### 1.2 Application process for the SILEO Open Call for Hack Day Travel Vouchers

To participate in the SILEO Open Call for Hack Day Travel Vouchers – Romania, applicants were required to complete the Application Form on the Cluster Submission Platform, where the SILEO Open Call was hosted.

The Application Form was divided into three main steps:

## D3.2 - SILEO Hack Days & Travel Vouchers scheme

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1. **Step 1: Submission of administrative data.** In the first step, applicants were asked to provide detailed administrative information about their company. This included essential data such as company name, address, legal status, contact details, and other relevant organizational information required to confirm their eligibility.
2. **Step 2: Upload of technical documentation.** The second step focused on the technical aspects of the application, where applicants were required to:
  - a. Select the challenge they intended to address from the predefined list of Hack Day challenges (e.g., digital optimization, sustainability, circular economy, etc.).
  - b. Provide a clear and concise explanation of their motivations for joining the Hack Day.
3. **Step 3: Upload of the signed Declaration of Honour.**

### 1.3 Summary results of the SILEO Open Call for Hack Day Travel Vouchers - Romania

A total of 30 SMEs applied for the SILEO Open Call for Hack Day Travel Vouchers – Romania.

This includes 27 SMEs from EU Member States (Romania, Italy, Spain, Slovenia, Sweden and Bulgaria) and 3 SMEs from Moldova, a country associated with the SMP under the agreement signed in September 2023, with retroactive effect starting on 01 January 2021.

#### 1.3.1 – Evaluation Process

The SILEO Quality Board, composed of representatives from the consortium’s partner organizations, carried out both the eligibility and quality assessment of each application.

The first step involved assessing the eligibility of both the applicant companies and their submitted proposals. This step ensured that all applications complied with the criteria set out in the Open Call guidelines, such as company type, geographical requirements, and proper submission of required documentation.

Applications that passed the eligibility check proceeded to a technical quality evaluation. This phase focused on assessing the applicants’ motivation for participating in the Hack Day event, as well as their potential contribution to addressing the key challenges identified in the furniture and lighting industries.

At the conclusion of the evaluation process, 28 companies successfully passed both the eligibility check and quality evaluation standards and were selected to receive funding (travel voucher).

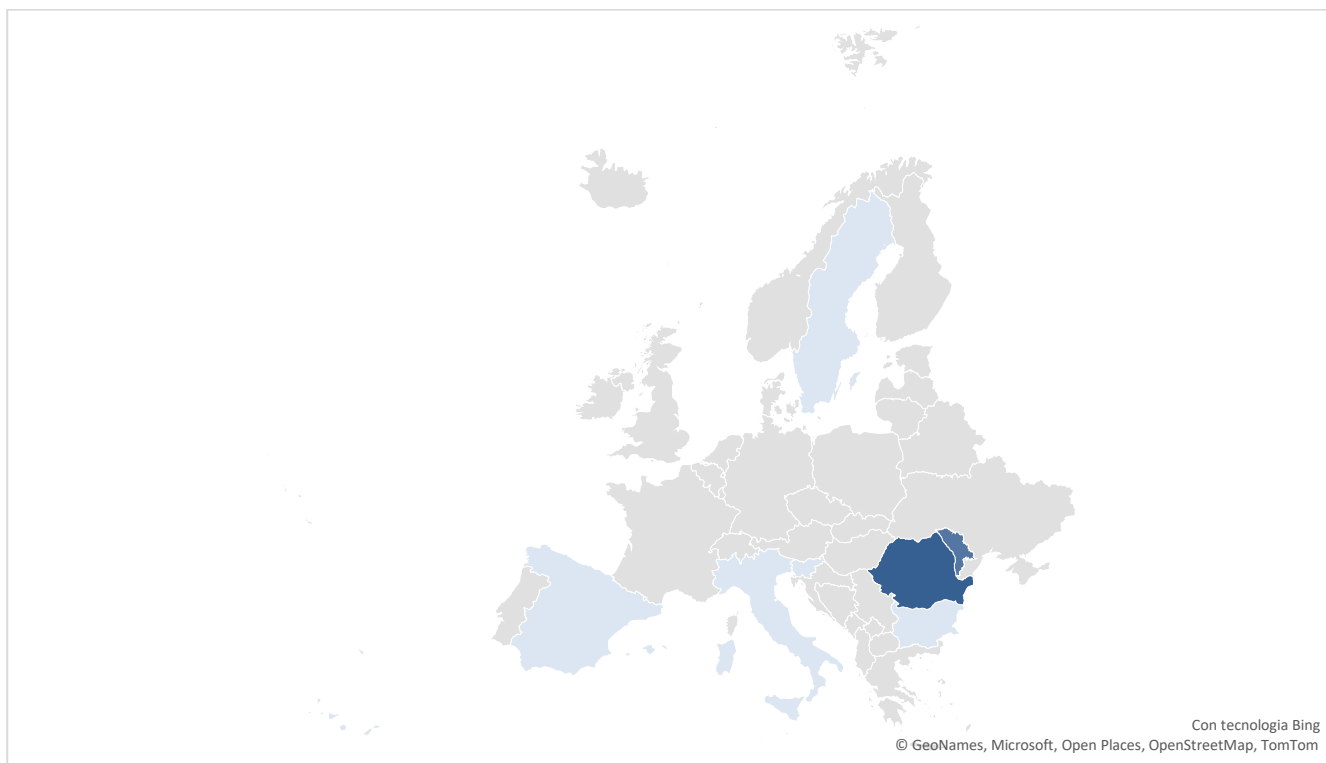
#### 1.3.2 – Sub-Grant Agreements and Voucher disbursement

The selected companies were invited to sign a Sub-Grant Agreement with the SILEO Consortium, which outlined the terms and conditions for the disbursement of travel vouchers and administrative provisions. The travel vouchers were awarded to the beneficiaries upon their participation in the Hack Day event held in Cluj-Napoca, Romania, on June 13-14, 2024.

#### 1.3.3 - Final outcome

In total, 24 companies participated in the SILEO Hack Day event in Cluj-Napoca and were successfully funded through the SILEO project. The total lump sum disbursed to the SMEs through the SILEO Open Call for Hack Day Travel Vouchers – Romania, amounted to € 10.000.

## D3.2 - SILEO Hack Days & Travel Vouchers scheme



### 1.4 Report of the Hack Day in Cluj-Napoca

The Hack Day in Romania, part of the SILEO project, took place on June 13-14, 2024, in Cluj-Napoca. It was designed to support SMEs in the furniture and lighting sectors, along with tech-savvy companies, to discuss industry challenges and find practical solutions.

The Hack Day in Romania was structured across two days, each with a specific focus and a mix of discussions, presentations, and networking opportunities:

- The first day started with registration and an introduction to the event's context and objectives. This was followed by a moderated discussion, where SMEs and technology providers exchanged views on the key digital and sustainability challenges affecting the furniture and lighting sectors. In the afternoon, participants had the chance to visit the CEM Center, a local hub for technological innovation. The day concluded with group reflections and a final session dedicated to summarizing the main outcomes and outlining the focus for the second day.
- The second day began with a pitching session, where tech-savvy companies presented their innovative solutions directly to participating SMEs. This was followed by a conclusion session, where the key takeaways and proposed solutions were reviewed and consolidated. The event wrapped up with a networking lunch, giving participants a valuable opportunity to establish new contacts and explore future collaboration possibilities.

## D3.2 - SILEO Hack Days & Travel Vouchers scheme

The Hack Day focused on three main topics: digital optimization in production, digital customer experience, and circular economy in furniture and lighting:

### I. Digital optimization in production

**1ST TOPIC**  
**DIGITALIZATION FOR**  
*Customization is an Illusion*

Digitalization should begin with the bidding process: Start digitalization early in the process, using digital tools to streamline and optimize the bidding, design, and production phases.

- Include less common options in the initial stages of design to avoid delays and complications later.
- A well-defined production process for raw materials is essential;

•Providing units that can be modified in size and function to fit different spaces and needs. This flexibility reduces the need for fully custom builds;

•Offering a wide range of colors and finishes as standard options provides the appearance of customization without the complexity;

**2ND TOPIC**

- Manual errors during measurement can lead to incorrect dimensions;
- Traditional methods are time-consuming, leading to longer project timelines and multiple visits may be required to confirm measurements;
- Incorrect measurements lead to cutting errors, resulting in wasted materials;

**3D SCAN**

**SOLUTIONS**

- Use 3D laser scanners for precise and quick measurements;
- Train staff thoroughly on the use of digital scanning tools
- Regularly update and refine digital tools and procedures based on feedback about price and cost;
- Calculate the total cost of equipment and compare it to the expected savings and additional revenue generated from improved efficiency and reduced waste.

**3D VISUALISATION**

**VIRTUAL ASSISTANT**  
TECHNICAL ISSUES

**MACHINE MALFUNCTIONS**

- Machine Malfunctions: The virtual assistant can monitor the status of machines in real-time and alert the maintenance team when a machine is down or experiencing issues;
- By analyzing data from sensors and historical trends, the virtual assistant can predict when a machine is likely to require maintenance, helping to prevent breakdowns before they occur;
- Provides step-by-step troubleshooting instructions to quickly resolve minor issues.
- Automatically send production and inventory data to the server, ensuring real-time updates of stock levels;
- Generate and send regular reports on production metrics, inventory levels, and machine performance;
- Enable employees to report issues quickly through voice or text commands, which can then be logged and tracked;
- Track the resolution status of reported issues and send follow-up notifications to

### II. Digital customer experience

14:00-17:00, 13TH OF JUNE

**CHALLENGE 2:**  
**DIGITAL CUSTOMER EXPERIENCE**

How can companies innovate in terms of digital customer experience, from purchase to customization?

**CHALLENGE 2: DIGITAL CUSTOMER EXPERIENCE**

PROBLEM/SOLUTION 3
<p><b>Describe the problem identified</b></p> <p>Customization of products—customers are unable to easily customize furniture and lighting products to meet their specific preferences and needs, leading to dissatisfaction and potential loss of sales.</p>
<p><b>Describe the solution</b></p> <ul style="list-style-type: none"> <li>-Real-time visualization: Implement real-time 3D visualization so customers can see changes instantly as they customize the product.</li> <li>-Offer <b>SOME</b> range of options: Offer a decent selection of customization options, including materials, colors, finishes, dimensions, and additional features. Avoid the paradox of choice.</li> </ul>
<p><b>What is the impact for the company?</b></p> <p>Brand differentiation Upselling and Cross-Selling Opportunities</p>

## D3.2 - SILEO Hack Days & Travel Vouchers scheme

### CHALLENGE 2: DIGITAL CUSTOMER EXPERIENCE

#### PROBLEM/SOLUTION 1

##### Describe the problem identified:

In the furniture and lighting industry, products often have unique designs, functionalities, and stories behind their creation. However, customers frequently encounter difficulty in grasping the full scope of these elements through digital channels. This disconnect can result in lower engagement, diminished perceived value, and ultimately, lost sales.

##### Describe the solution:

Detailed Storytelling  
Multimedia Content  
Virtual Tours and Demos  
AR Visualization

##### What is the impact for the company?

Enhanced Customer Experience  
Increased Sales and Revenue  
Stronger Brand Loyalty

## III. Circular economy in furniture & lighting

### CIRCULAR ECONOMY IN FURNITURE & LIGHTING

The concept is comprising the process of **rethinking product design, production processes, and end-of-life strategies and upcycling** to minimize waste and maximize resource efficiency, from product development to recycling and reintegrating it into the same or a different value-chain.

In 2022, the rate of circularity of material use in the EU was 11.5 %, 3.3 percentage points (pp) up from 2004.

**11.5%**

Designing lighting products that are modular and easy to disassemble for repair, reuse, or recycling can be technically complex. Components need to be standardized and easily separable, which is often not the case with current design

14:00-17:00, 13TH OF JUNE

### CHALLENGE 3: CIRCULAR ECONOMY IN FURNITURE & LIGHTING

How can companies  
implement circular  
economy models for  
their products?



### CHALLENGE 3: CIRCULAR ECONOMY IN FURNITURE & LIGHTING

#### PROBLEM/SOLUTION 1

##### Describe the problem identified:

##### Regulations, Standards, and Green Washing

There is a lot of legislation related to the circular economy from different fields – it is complicated for companies to identify and keep under control the aspects they need to comply with. Standardization and certification is an area where small and medium-sized enterprises (SMEs) do not have the resources for investments and find it too bureaucratic. Green Washing – difficult to prove both for the public and for companies regarding green claims.

##### Describe the solution:

Be part of a network and share the knowledge, expertise and experience

##### What is the impact for the company?

Finding and adapting tools, theory, and information easily to become more sustainable.

### CHALLENGE 3: CIRCULAR ECONOMY IN FURNITURE & LIGHTING

#### PROBLEM/SOLUTION 2

##### Describe the problem identified:

##### New business models, Developing new culture, and Strategic thinking:

Small and medium enterprises are too busy with operational activities (short term strategy) and lack the time to discover sustainable solutions. They only take steps in this direction when constrained by the market.

##### Describe the solution:

Sustainability means long term planning.  
- Raising awareness of financing solutions.

##### What is the impact for the company?

- Better products, better branding, applying circular thinking to everyday activities.

## D3.2 - SILEO Hack Days & Travel Vouchers scheme

Photos:



## D3.2 - SILEO Hack Days & Travel Vouchers scheme

### 2. Hack Day in Padua (Italy) on 16.10.2024



**SILEO**  
Co-funded by the European Union

**OPEN CALL FOR HACK-DAY TRAVEL VOUCHERS – ITALY**

**16 Oct 24 PADUA (IT)**

SILEO Hack-Day "IMPACT - Development of innovative business ideas for SMEs in the Furniture & Lighting Industry" is a platform for SMEs to explore innovative solutions, connect with experts in emerging technologies and sustainable growth, and discuss on specific challenges, such as **Data integration, IoT devices and mobile app, AR/VR and new materials** for the lighting & furniture value chain.

Eligible applicants:

- Lighting/Furniture SMEs
- Tech-savvy SMEs

**DEADLINE** 28.06.2024 17:00 CEST

**VOUCHER** EUR 150, EUR 250, EUR 500

**APPLY NOW** via the Cluster Submission Platform

SILEO Consortium launched a targeted call titled “**SILEO Open Call for Hack Day Travel Vouchers – Padua, Italy**”, to facilitate the participation of SMEs in the lighting and furniture sectors, as well as tech-savvy SMEs, in the SILEO Hack Day event titled “*IMPACT – Development of Innovative Business Ideas for SMEs in the Furniture & Lighting Industry*”. The event was organized by Rete di Imprese Luce in Veneto and took place on October 16, 2024 in Padua, Italy.

The Open Call was active from 29.04.2024 (10:00 AM) to 28.06.2024 (17:00 PM) and was hosted on the Cluster

Submission Portal: [https://clustersubmissionplatform.eu/eurocluster\\_post/sileo-open-call-for-hack-day-travel-vouchers-padua-italy/](https://clustersubmissionplatform.eu/eurocluster_post/sileo-open-call-for-hack-day-travel-vouchers-padua-italy/)

The Hack Day in Italy was strategic schedule alongside the Italian fair “IMPACT – La Fiera dei Servizi e dell’Innovazione per l’impresa”, held on 16-17 October 2024 in Padua. The Hack Day was designed to provide a collaborative platform where SMEs and tech-savvy SMEs could network, gain new insights, explore innovative solutions and technologies and discuss on specific challenges relevant to the lighting and furniture industries:

1. **DATA INTEGRATION:** The role and impact of data integration in optimizing manufacturing processes.
2. **IOT DEVICES AND MOBILE APP:** Leveraging IoT and new communication technologies for developing innovative (new) products and services.
3. **VIRTUAL AND AUGMENTED REALITY:** Enhancing design, manufacturing and customer experiences through virtual and augmented reality technologies.
4. **NEW MATERIALS AND CIRCULAR ECONOMY:** Exploring the use of innovative materials and circular economy principles to improve product and service sustainability in design and manufacturing.

#### 2.1 Travel voucher categories and funding

To encourage participation, the SILEO Consortium offered **65 travel vouchers**, divided into two categories:

- **50 vouchers** for SMEs in the lighting or furniture industries.
- **15 vouchers** for tech-savvy SMEs, specializing in innovative and green solutions.

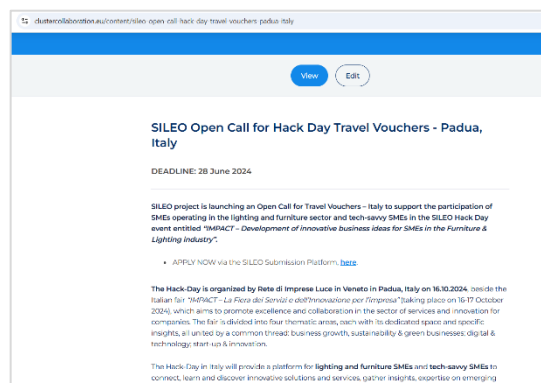
The travel vouchers were provided based on the SME’s legal headquarters location, as detailed below:

- ❖ Legal headquarters located in the Province of Padua – voucher amount: 150 EUR
- ❖ Legal headquarters located in the Veneto Region (excluding the Province of Padua) – voucher amount: 250 EUR
- ❖ Legal headquarters located outside the Veneto Region – voucher amount: 500 EUR

In addition to travel vouchers, 15 tech-savvy SMEs (selected based on their scores in the quality evaluation) were granted a booth at the IMPACT Fair. This allowed them to showcase their products, services, technological innovations, and promotional materials to an international audience.

The Open Call was extensively promoted through SILEO's social media channels, particularly on its LinkedIn page, as well as on the websites and social media channels of its partners. Additionally, it was advertised on key platforms such as the European Cluster Collaboration Platform, the Funding & Tenders portal, and various relevant industry and magazine websites.

## D3.2 - SILEO Hack Days & Travel Vouchers scheme



### 2.2 Application process for the SILEO Open Call for Hack Day Travel Vouchers

To participate in the SILEO Open Call for Hack Day Travel Vouchers – Padua, Italy, applicants were required to complete the Application Form on the Cluster Submission Platform, where the SILEO Open Call was hosted.

The Application Form was divided into three main steps:

- Step 1: Submission of administrative data.** In the first step, applicants were asked to provide detailed administrative information about their company. This included essential data such as company name, address, legal status, contact details, and other relevant organizational information required to confirm their eligibility.
- Step 2: Upload of technical documentation.** The second step focused on the technical aspects of the application, where applicants were required to:
  - Select the challenge they intended to address from the predefined list of Hack Day challenges (e.g., data integration, IoT, AR/VR, etc.)
  - Provide a clear and concise explanation of their motivations for joining the Hack Day.
- Step 3: Upload of the signed Declaration of Honour.**

### 2.3 Summary results of the SILEO Open Call for Hack Day Travel Vouchers – Padua, Italy

A total of 48 SMEs applied for the SILEO Open Call for Hack Day Travel Vouchers – Padua, Italy. This includes SMEs from Italy, France, Romania and Sweden.

#### 2.3.1 – Evaluation Process

The SILEO Quality Board, composed of representatives from the consortium's partner organizations, carried out both the eligibility and quality assessment of each application.

The first step involved assessing the eligibility of both the applicant companies and their submitted proposals. This step ensured that all applications complied with the criteria set out in the Open Call guidelines, such as company type, geographical requirements, and proper submission of required documentation.

Applications that passed the eligibility check proceeded to a technical quality evaluation. This phase focused on assessing the applicants' motivation for participating in the Hack Day event, as well as their potential contribution to addressing the key challenges identified in the furniture and lighting industries.

After the evaluation process, 45 companies successfully passed both the eligibility check and quality evaluation standards and were selected to receive funding (travel voucher).

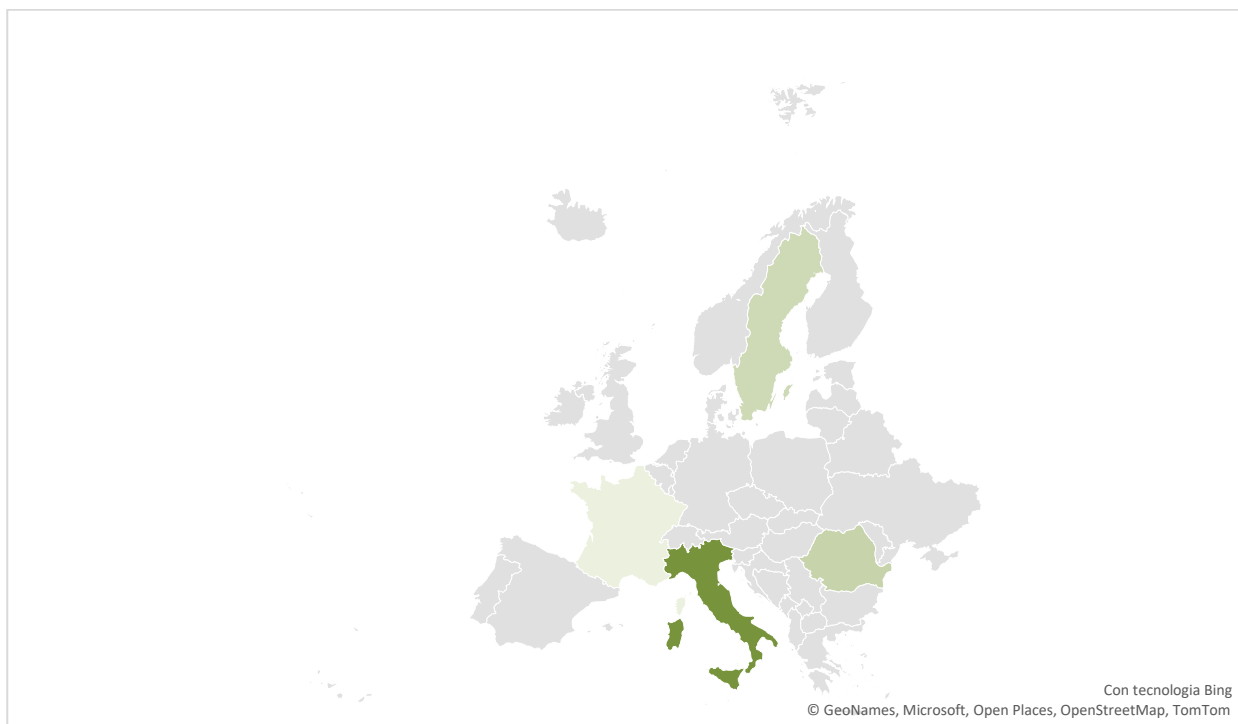
## D3.2 - SILEO Hack Days & Travel Vouchers scheme

### 2.3.2 – Sub-Grant Agreements and Voucher disbursement

The selected companies were invited to sign a Sub-Grant Agreement with the SILEO Consortium, which outlined the terms and conditions for the disbursement of travel vouchers and administrative provisions. The travel vouchers were awarded to the beneficiaries upon their participation in the Hack Day event held in Padua, Italy on 16 October 2024.

### 2.3.3 - Final outcome

In total, 40 companies participated in the SILEO Hack Day event in Padova and were successfully funded through the SILEO project. The total lump sum disbursed to the SMEs through the SILEO Open Call for Hack Day Travel Vouchers – Padua, Italy, amounted to € 16.450.



## D3.2 - SILEO Hack Days & Travel Vouchers scheme

### 2.4 Report of the Hack Day in Italy

# SILEO HACK-DAY

## PADUA - ITALY

**IMPACT - Development of innovative business ideas for SMEs in the Furniture & Lighting industry**

Padova Fiere, Pavilion 5  
Via N. Tommaseo, 59, 35131 Padua

16 October 2024  
09:00-18:00

### SILEO HACK-DAY AGENDA

**09:00** Exhibitors' registration (tech-savvy SMEs entry)

**09:30** Visitors' registration (SMEs entry)

**10:00-10:30** WORKSHOP AREA "SERGIO MARCHIONNE" - Presentation of the SILEO project and its business support actions

**10:30-13:00** WORKSHOP AREA "SERGIO MARCHIONNE": Pitch presentation of tech-savvy SMEs' solutions and services addressing SILEO challenges

1. Lightcube srl
2. EDALAB srl
3. VIEUP srl
4. Materially srl Impresa Sociale
5. Lingon Certificates AB
6. ADV GROUP di Paronuzzi Federico
7. Cubit s.c.a.r.l
8. Trailslight srl
9. DryTech srl
10. SD Virtual Config srl
11. Rawfish srl a Socio Unico
12. To Be srl
13. Skelholding srl
14. SD Companies srl
15. Essentials Service Technology

**13:00-14:00** Launch break

**14:30-16:30** SILEO Eurocluster space (stand F14): B2B meetings between tech-savvy SMEs and lighting-furniture SMEs and other technology providers

**16:30-18:00** SILEO Eurocluster space (stand F14): Networking session with all participants



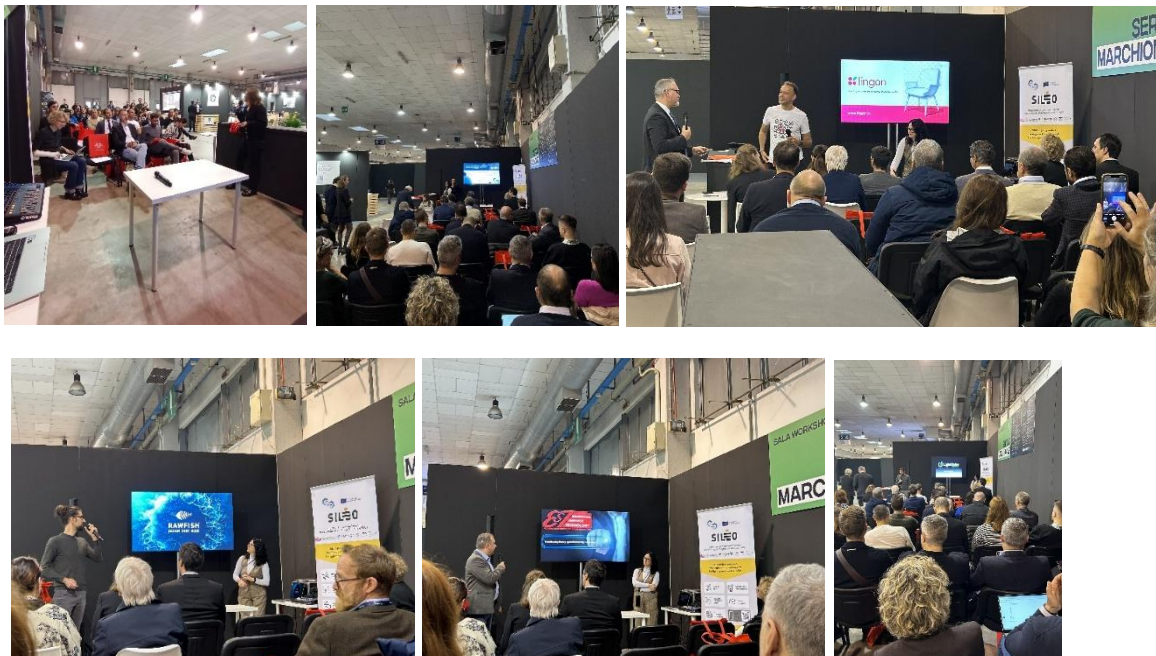


The Hack Day in Padua was organized into two engaging sessions, each designed to foster collaboration, knowledge sharing and innovation.

The morning session took place at the "SERGIO MARCHIONI" Workshop Area and kicked off with an informative presentation of the SILEO Eurocluster project by Marta Krakowiak (ELCA European Lighting Cluster Alliance – SILEO coordinator). This session provided attendees with a detailed overview of the project's impact on the lighting and furniture sectors and funding opportunities for SMEs, including the 2nd Call for Advanced Technology Uptake Projects and the Best Company Story-Telling Video Contest.

The morning continued with a pitch session 15 where tech-savvy SMEs took the stage to present their innovative business models and cutting-edge technologies to address key challenges and contribute to the sectors' sustainability. The pitch session provided a valuable opportunity for these tech-savvy companies to connect with potential partners, clients, and collaborators, while also gaining visibility in a sector poised for transformation.

Photos:

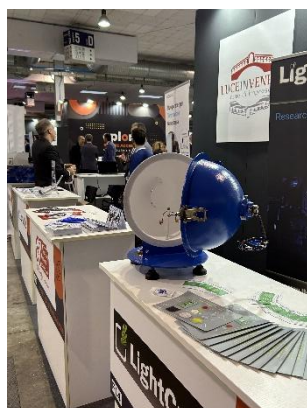


The afternoon session of the Hack Day offered a unique hands-on experience, beginning with a guided tour of the SILEO Eurocluster space located at stand F14. This dedicated area featured 14 desks, each showcasing innovative products, services, and solutions from tech-savvy companies. After the tour, participants were provided with the opportunity to schedule B2B meetings with the exhibiting companies. These one-on-one meetings allowed attendees to engage directly with the exhibitors, explore potential collaborations, discuss

## D3.2 - SILEO Hack Days & Travel Vouchers scheme

business opportunities, and gain deeper insights into the cutting-edge technologies and solutions presented throughout the day. This session aimed to foster meaningful connections and drive partnerships within the lighting and furniture sectors.

*Photos:*



The event attracted over 70 attendees, including representatives from the participating companies and members of the SILEO cluster. Additionally, the SILEO stand at the IMPACT Fair attracted more than 450 visitors, demonstrating a high level of interest and engagement from the broader community.

To ensure that the knowledge and insights from the event were accessible to all, a Drive folder containing the presentation slides for the SILEO project and the participating tech-savvy SMEs, along with photos from the event, was shared with all attendees by Rete di Imprese Luce in Veneto. This provided participants with a valuable resource to revisit the event's content and foster continued collaboration.